

Features

- Free from secondary breakdown
- Low power drive requirement
- Ease of paralleling
- ► Low C_{LSS} and fast switching speeds
- High input impedance and high gain

Applications

- Motor controls
- Converters
- Amplifiers
- Switches
- Power supply circuits
- Drivers (relays, hammers, solenoids, lamps, memories, displays, bipolar transistors, etc.)

General Description

The Supertex VN2110 is an enhancement-mode (normallyoff) transistor that utilizes a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces a device with the power handling capabilities of bipolar transistors, and the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, this device is free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Ordering Information

Device	Package	Options	BV _{pss} /BV _{pgs}	R _{DS(ON)} (max)		
	TO-236AB (SOT-23)	Die*	(V)	(max) (Ω)		
VN2110	VN2110K1-G	VN2110ND	100	4.0		

-G indicates package is RoHS compliant ('Green')

* MIL visual screening available.



Pin Configuration



Absolute Maximum Ratings

Parameter	Value
Drain-to-source voltage	BV _{DSS}
Drain-to-gate voltage	BV _{DGS}
Gate-to-source voltage	±20V
Operating and storage temperature	-55°C to +150°C
Soldering temperature*	+300°C

Absolute Maximum Ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied. Continuous operation of the device at the absolute rating level may affect device reliability. All voltages are referenced to device ground.

* Distance of 1.6mm from case for 10 seconds.

Thermal Characteristics

Package	l _D (continuous) [†] (mA)	Ι _D (pulsed) (mA)	Power Dissipation @T _A = 25°C (W)	θ _{jc} (°C/W)	θ _{ja} (°C/W)	l _{DR} [†] (mA)	I _{DRM} (mA)
TO-236AB (SOT-23)	200	800	0.36	200	350	200	800

Notes:

† I_{D} (continuous) is limited by max rated T_{i} .

Electrical Characteristics (T_A = 25°C unless otherwise specified)

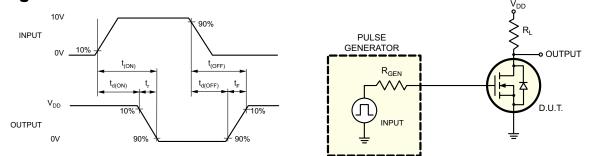
$(I_A - 25)$ C unless otherwise specified)									
Sym	Parameter	Min	Тур	Max	Units	Conditions			
BV _{DSS}	Drain-to-source breakdown voltage	100	-	-	V	V _{GS} = 0V, I _D = 1.0mA			
V _{GS(th)}	Gate threshold voltage	0.8	-	2.4	V	$V_{GS} = V_{DS}, I_{D} = 1.0 \text{mA}$			
$\Delta V_{GS(th)}$	Change in $V_{GS(th)}$ with temperature	-	-3.8	-5.5	mV/ºC	$V_{GS} = V_{DS}, I_{D} = 1.0 \text{mA}$			
I _{GSS}	Gate body leakage current	-	0.1	100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$			
		-	-	1.0		V_{GS} = 0V, V_{DS} = Max Rating			
I _{DSS}	Zero gate voltage drain current	-	-	100	μA	$V_{DS} = 0.8$ Max Rating, $V_{GS} = 0V$, $T_A = 125^{\circ}C$			
I _{D(ON)}	On-state drain current	0.6	-	-	A	V _{GS} = 10V, V _{DS} = 25V			
		-	4.5	6.0	0	V _{GS} = 5.0V, I _D = 75mA			
R _{DS(ON)}	Static drain-to-source on-state resistance	-	3.0	4.0	Ω	V _{GS} = 10V, I _D = 500mA			
$\Delta R_{DS(ON)}$	Change in $R_{\scriptscriptstyle DS(ON)}$ with temperature	-	0.7	1.0	%/°C	V _{GS} = 10V, I _D = 500mA			
G _{FS}	Forward transconductance	150	400	-	mmho	V _{DS} = 25V, I _D = 500mA			
C _{ISS}	Input capacitance	-	35	50		V _{GS} = 0V,			
C _{oss}	Common source output capacitance	-	13	25	pF	V _{DS} = 25V,			
C _{RSS}	Reverse transfer capacitance	-	4.0	5.0		f = 1.0MHz			
t _{d(ON)}	Turn-on delay time	-	3.0	5.0					
t,	Rise time	-	5.0	8.0	ns	$V_{DD} = 25V,$			
t _{d(OFF)}	Turn-off delay time	-	6.0	9.0	115	$I_{D} = 600 \text{mA},$ $R_{GEN} = 25\Omega$			
t _r	Fall time	-	5.0	8.0		GLN			
V _{SD}	Diode forward voltage drop	-	1.2	1.8	V	V _{GS} = 0V, I _{SD} = 600mA			
t _{rr}	Reverse recovery time	-	400	-	ns	V _{GS} = 0V, I _{SD} = 600mA			

Notes:

1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300µs pulse, 2% duty cycle.)

2. All A.C. parameters sample tested.

Switching Waveforms and Test Circuit



VN2110

V_{GS} =

10V

9V

8V

7V

6V

5V

4V

3V

10

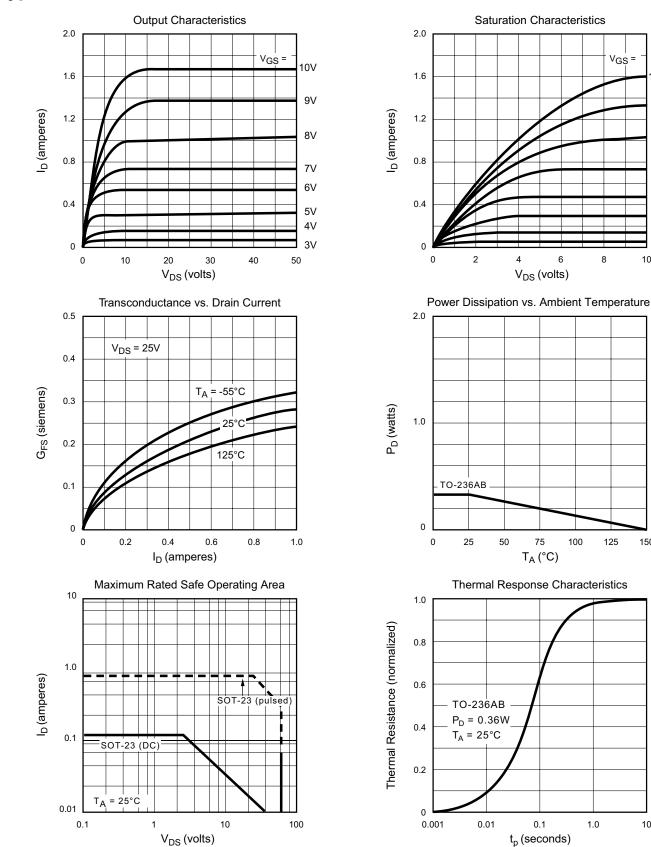
8

125

1.0

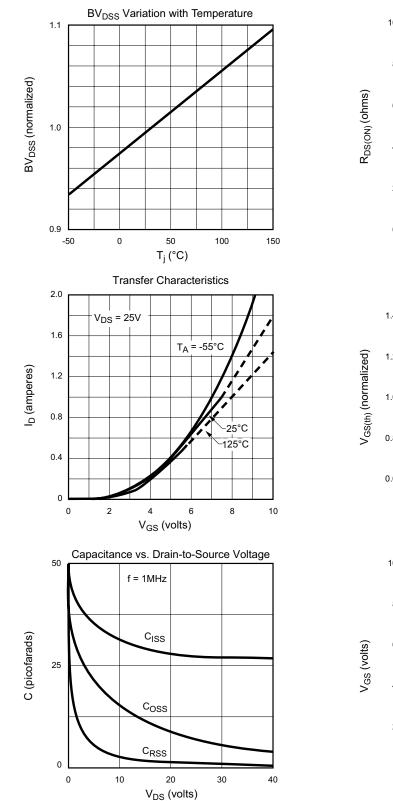
10

150

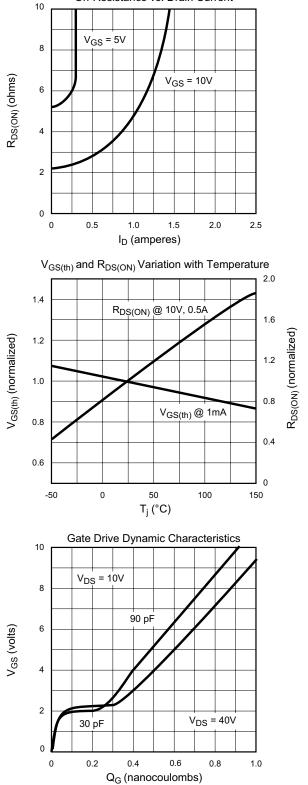


Typical Performance Curves

VN2110



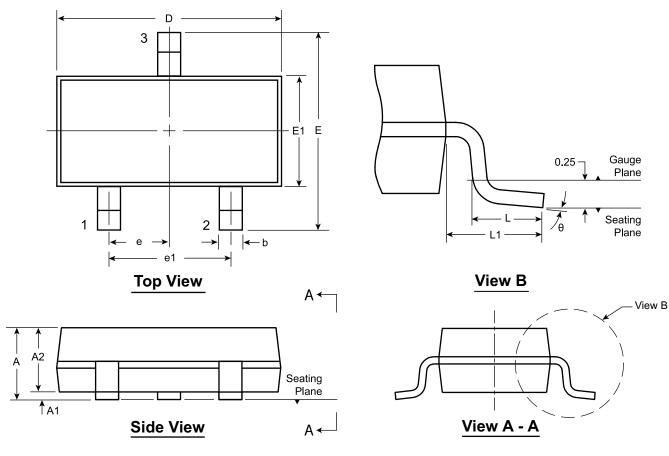
Typical Performance Curves (cont.)



On-Resistance vs. Drain Current

3-Lead TO-236AB (SOT-23) Package Outline (K1)

2.90x1.30mm body, 1.12mm height (max), 1.90mm pitch



Symb	ol	Α	A1	A2	b	D	E	E1	е	e1	L	L1	θ		
Dimension (mm)	MIN	0.89	0.01	0.88	0.30	2.80	2.10	1.20	0.05	1.90 BSC	4.00		0.20†		0 0
	NOM	-	-	0.95	-	2.90	-	1.30	0.95 BSC		0.50 0.54 REF	-			
	MAX	1.12	0.10	1.02	0.50	3.04	2.64	1.40	500			0.60		8 0	

JEDEC Registration TO-236, Variation AB, Issue H, Jan. 1999.

† This dimension is a non-JEDEC dimension.

Drawings not to scale.

Supertex Doc.#: DSPD-3TO236ABK1, Version B072208.

(The package drawing (s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <u>http://www.supertex.com/packaging.html</u>.)

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